



Material Content Data Sheet



Sales Product Name		TLS115D0LD		Issued		22. July 2019		
MA#		MA005350789						
Package		PG-TSON-10-2		Weight*		31.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.123	3.54	3.54	35363	35363
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8356	
wire	non noble metal	copper	7440-50-8	10.773	33.93	34.82	339288	348166
	non noble metal	copper	7440-50-8	0.036	0.11	0.11	1143	1143
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1175
plastics	plastics	epoxy resin	-	1.922	6.05		60519	
	inorganic material	silicondioxide	60676-86-0	16.697	52.58	58.75	525867	587561
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11656	11656
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2024	2024
glue	plastics	epoxy resin	-	0.112	0.35		3522	
	noble metal	silver	7440-22-4	0.335	1.06	1.41	10565	14087
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com